

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	614	156/345.ccls or 261/067.ccls. or 118/723ve,723r.ccls.	USPAT	OR	ON	2001/05/29 10:58
S2	614	156/345.ccls or 261/067.ccls. or 118/723ve.ccls. or 118/723r.ccls.	USPAT	OR	ON	2001/05/29 10:58
S3	57	(156/345.ccls or 261/067.ccls. or 118/723ve.ccls. or 118/723r.ccls.) and "applied materials".as.	USPAT	OR	ON	2001/05/29 11:31
S4	485	(156/345.ccls or 261/067.ccls. or 118/723ve.ccls. or 118/723r.ccls.) and plasma	USPAT	OR	ON	2001/05/29 11:03
S5	1	"5646814".pn. and "54"	USPAT	OR	ON	2001/05/29 11:31
S6	103410	polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization"	USPAT	OR	ON	2001/06/12 13:14
S7	25434	(polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (wafer semiconductor ic "integrate circuit")	USPAT	OR	ON	2001/06/12 11:21
S8	1371	((polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (wafer semiconductor ic "integrate circuit")) and (156/345 or "441"/\$ or "216"/\$).ccls.	USPAT	OR	ON	2001/06/12 11:22
S9	0	(((polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (wafer semiconductor ic "integrate circuit")) and (156/345 or "441"/\$ or "216"/\$).ccls.) and "dress ring"	USPAT	OR	ON	2001/06/12 11:49
S10	23421	kobayashi-\$.\$in. or tanaka-\$.\$in.	USPAT	OR	ON	2001/06/12 11:49
S11	0	(kobayashi-\$.\$in. or tanaka-\$.\$in.) and "mitsubishi materials corporation".as.	USPAT	OR	ON	2001/06/12 11:50
S12	1015	(kobayashi-\$.\$in. or tanaka-\$.\$in.) and (polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization")	USPAT	OR	ON	2001/06/12 11:51
S13	2334	(polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ring near10 (carrier head platen pad)	USPAT	OR	ON	2001/06/12 13:15

S14	78	((polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (wafer semiconductor ic "integrate circuit")) and (156/345 or "441"/\$ or "216"/\$).ccls.) AND ((polish\$3 or abrad\$3 or CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ring near10 (carrier head platen pad))	USPAT	OR	ON	2001/06/12 13:15
S15	163	"118"/\$.ccls. and (que\$3 hold\$3 wait\$3) and (paddle)	USPAT	OR	ON	2001/11/14 12:02
S16	811	(semiconductor wafer) and (que\$3 hold\$3 wait\$3) and (paddle)	USPAT	OR	ON	2001/11/14 12:02
S17	759	((semiconductor wafer) and (que\$3 hold\$3 wait\$3) and (paddle)) not ("118"/\$.ccls. and (que\$3 hold\$3 wait\$3) and (paddle))	USPAT	OR	ON	2001/11/14 12:03
S18	6	("4477311" "4547247" "4548699" "4563240" "4584045" "4592306").PN.	USPAT	OR	ON	2001/11/14 12:13
S19	38479	extract\$3 and slurry	USPAT	OR	ON	2001/11/15 12:10
S20	12341	extract\$3 same slurry	USPAT	OR	ON	2001/11/15 12:10
S21	34	(extract\$3 same slurry) and (chemical adj mechanical adj (polishing planarization))	USPAT	OR	ON	2001/11/15 12:20
S22	56	((gas vapor) near10 slurry) and (chemical adj mechanical adj (polishing planarization))	USPAT	OR	ON	2001/11/15 12:40
S23	0	(microporous adj fiber) and (chemical adj mechanical adj (polishing planarization))	USPAT	OR	ON	2001/11/15 12:41
S24	365	(fiber) and (chemical adj mechanical adj (polishing planarization))	USPAT	OR	ON	2001/11/15 12:42
S25	26	(gas near10(fiber)) and (chemical adj mechanical adj (polishing planarization))	USPAT	OR	ON	2001/11/15 12:53
S26	56	extractor and contactor and fibers	USPAT	OR	ON	2001/11/15 13:03
S27	20	(extractor and contactor and fibers) and hydrophobic	USPAT	OR	ON	2001/11/15 13:35
S28	1	"3277947"	JPO; DERWENT	OR	ON	2001/11/15 13:36
S29	2	"03277947"	JPO; DERWENT	OR	ON	2001/11/15 13:36
S30	1	"4967777".pn.	USPAT	OR	ON	2001/11/16 16:49
S31	16	"4967777"	USPAT	OR	ON	2001/11/16 17:03

S32	13295	(wet adj (etch\$3))	USPAT	OR	ON	2001/11/16 17:04
S33	1632	((wet adj (etch\$3))) and (dip\$4)	USPAT	OR	ON	2001/11/16 17:04
S34	1465	((wet adj (etch\$3))) and immers\$3	USPAT	OR	ON	2001/11/16 17:05
S35	2794	(((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)	USPAT	OR	ON	2001/11/16 17:05
S36	1327	(((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (lift vertical)	USPAT	OR	ON	2001/11/16 17:06
S37	1418	((((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (lift vertical)) or (((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (156/345.cccls. or "134"/\$.cccls.))	USPAT	OR	ON	2001/11/16 17:06
S38	162	((((((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (lift vertical)) or (((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (156/345.cccls. or "134"/\$.cccls.))) and (156/345.cccls. or "134"/\$.cccls.)	USPAT	OR	ON	2004/08/20 22:13
S39	22	("5868898") or ("5839456") or ("5827396") or ("5730162") or ("5698038") or ("5415698") or ("5188701") or ("6228211") or ("6281136") or ("6090720") or ("6071374") or ("6054062") or ("5464480") or ("5976311") or ("5776296") or ("5672212") or ("5174855") or ("5904572") or ("5804516") or ("5698040") or ("5817185") or ("6276379")).PN.	USPAT; USOCR	OR	OFF	2002/06/25 12:38
S40	8	"5904608"	USPAT	OR	ON	2001/11/30 09:53
S41	1	"5976311".pn.	USPAT	OR	ON	2001/11/30 10:41
S42	607	((wet or dip\$3) same (bubbly\$3 sparger "stream plate")) and (156/345\$.cccls. or etch\$3)	USPAT	OR	OFF	2004/08/20 22:32
S43	96	((wet or dip\$3) same (bubbly\$3 sparger "stream plate")) and (etch\$3)	EPO; JPO; DERWENT	OR	OFF	2002/06/25 13:38
S44	124	(((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (156/345.cccls. or "134"/\$.cccls.)	USPAT	OR	ON	2002/09/25 09:31
S45	267	((wet adj (etch\$3)) and (dip\$4)) or ((wet adj (etch\$3)) and immers\$3)	EPO; JPO; DERWENT	OR	ON	2004/08/20 22:31

S46	171	(((((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (lift vertical)) or (((((wet adj (etch\$3))) and (dip\$4)) or (((wet adj (etch\$3))) and immers\$3)) and (156/345.ccls. or "134"/\$.ccls.))) and (156/345. ccls. or "134"/\$.ccls.)	USPAT	OR	ON	2004/08/20 22:13
S47	1066	((wet dip\$4) same (process\$3 etch\$3)) and((guide support) with (notch stopper groove))	USPAT	OR	OFF	2004/08/20 22:33
S48	24	((wet dip\$4) with (process\$3 etch\$3)) same((guide support) with (notch stopper groove))	USPAT	OR	OFF	2004/08/20 22:34
S49	15	((((wet dip\$4) with (process\$3 etch\$3)) same((guide support) with (notch stopper groove))) same (wafer substrate semiconductor)	USPAT	OR	OFF	2004/08/20 22:35
S50	211284	wet adj etch\$3) (dip\$4) (isotropic\$4	USPAT	OR	OFF	2004/08/20 22:36
S51	48556	(wet adj etch\$3) (dip\$4) (isotropic\$4) and (wafer semiconductor)	USPAT	OR	OFF	2004/08/20 22:36
S52	21587	((wet adj etch\$3) (dip\$4) (isotropic\$4) and (wafer semiconductor)) and (156/345.\$. "216"/\$ "438"/\$ "134"/\$)	USPAT	OR	OFF	2004/08/20 22:37
S53	986	((((wet adj etch\$3) (dip\$4) (isotropic\$4) and (wafer semiconductor)) and (156/345.\$. "216"/\$ "438"/\$ "134"/\$)) and (guide)	USPAT	OR	OFF	2004/08/20 22:37
S54	218	((((wet adj etch\$3) (dip\$4) (isotropic\$4) and (wafer semiconductor)) and (156/345.\$. "216"/\$ "438"/\$ "134"/\$)) and (guide)) and (notch stopper slot)	USPAT	OR	ON	2004/08/20 22:38
S55	28	("3899372" "3934733" "4171740" "4219835" "4256229" "4256514" "D260237" "4471716" "4573851" "4574950" "4653636" "4817795" "4949848" "5025926" "5101976" "5111936" "5370142" "5464480" "5605246" "5632374" "5704494" "5706946" "5725101" "5782361" "5782362" "5862823" "5921397" "5960960").PN.	USPAT	OR	OFF	2004/08/20 22:53
S56	1	"4256229".pn.	USPAT	OR	ON	2004/08/23 10:08
S57	137	robot and (156/345.11 156/345.51 134/113 134/135)	USPAT	OR	ON	2004/08/23 10:45

S58	439	arm and (156/345.11 156/345.51 134/113 134/135)	USPAT	OR	ON	2004/08/23 10:46
S59	351	(arm and (156/345.11 156/345.51 134/113 134/135)) not (robot and (156/345.11 156/345.51 134/113 134/135))	USPAT	OR	ON	2004/08/23 12:08
S60	2	"07164328"	JPO; DERWENT	OR	ON	2004/08/23 12:10
S61	0	"200450315"	JPO; DERWENT	OR	ON	2004/08/23 12:10
S63	37554	(arm transfer robot) and (h01l021\$. ipc. h05h001\$.ipc. b08b07\$.ipc.)	JPO; DERWENT	OR	ON	2005/01/24 13:47
S64	5332	S63 and (etch\$3 remov\$3)	JPO; DERWENT	OR	ON	2005/01/24 13:48
S65	452	S64 and (boat holder guide\$1)	JPO; DERWENT	OR	ON	2005/01/24 13:48